

# MA2J727

## Silicon epitaxial planar type

For super high speed switching

For small current rectification

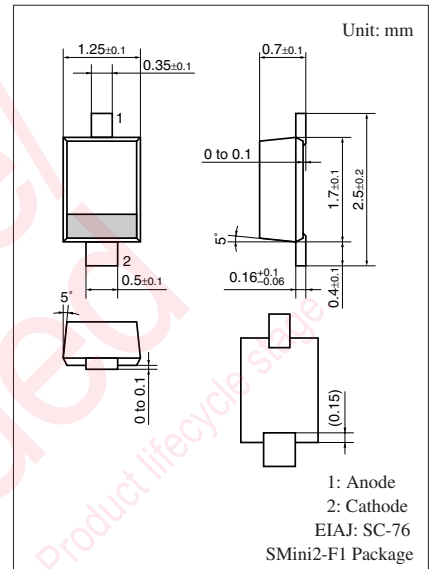
### ■ Features

- $V_R = 50$  V is guaranteed
- $I_{F(AV)} = 200$  mA rectification is possible

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	50	V
Repetitive peak reverse voltage	$V_{RRM}$	50	V
Peak forward current	$I_{FM}$	300	mA
Forward current (Average)	$I_{F(AV)}$	200	mA
Non-repetitive peak forward surge current *	$I_{FSM}$	1	A
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

Note) \*: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)



Marking Symbol: 2F

### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

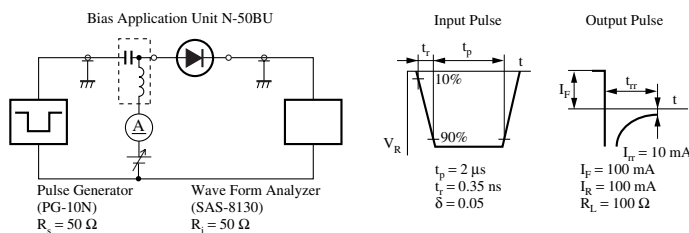
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse current	$I_R$	$V_R = 50$ V			200	$\mu\text{A}$
Forward voltage	$V_{F1}$	$I_F = 30$ mA			0.36	V
	$V_{F2}$	$I_F = 200$ mA			0.55	V
Terminal capacitance	$C_t$	$V_R = 0$ V, $f = 1$ MHz		30		pF
Reverse recovery time *	$t_{rr}$	$I_F = I_R = 100$ mA $I_{rr} = 10$ mA, $R_L = 100 \Omega$		3.0		ns

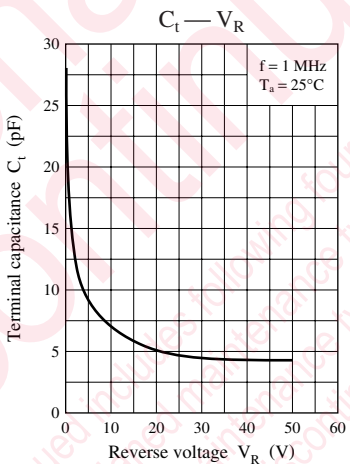
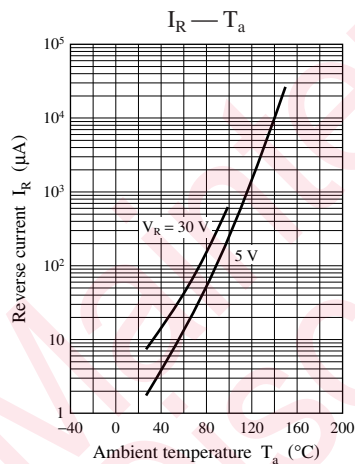
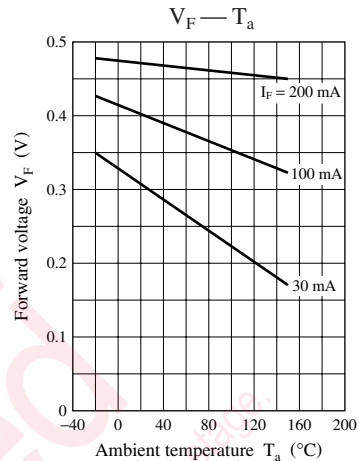
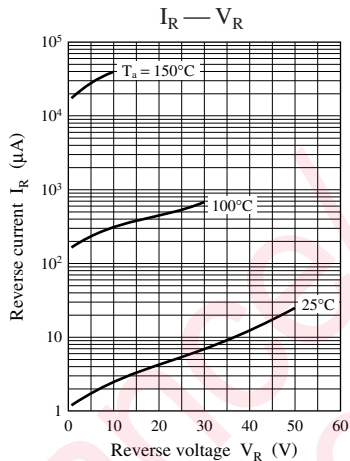
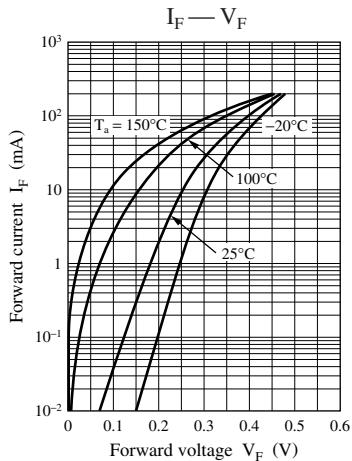
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. Absolute frequency of input and output is 1 GHz.

4. \*:  $t_{rr}$  measurement circuit





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